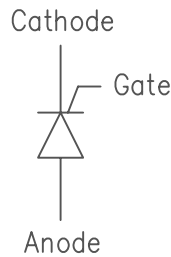
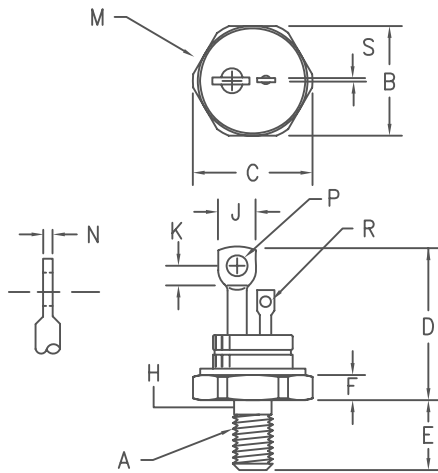


# Silicon Controlled Rectifier Series 051



Dim.	Inches		Millimeter		Notes
	Minimum	Maximum	Minimum	Maximum	
A	---	---	---	---	1
B	.677	.685	17.20	17.40	
C	---	.770	---	19.56	
D	1.200	1.350	30.48	34.29	
E	.427	.455	10.84	11.55	
F	.115	.155	2.92	3.94	
G	---	.600	---	15.24	
H	.220	.249	5.58	6.32	2
J	.200	.300	5.08	7.62	
K	.120	---	3.05	---	
M	---	.680	---	17.27	Dia.
N	.030	.060	.762	1.52	
P	.170	.180	4.32	4.57	Dia.
R	.055	.065	1.40	1.65	Dia.
S	.025	.030	.64	.76	

Note 1: 1/4-28 UNF-3A

Note 2: Full thread within 2 1/2 threads

## TO-208AC (TO-65) CERAMIC

Microsemi Catalog Number	Forward & Reverse Repetitive Blocking VDRM, VRRM	Reverse Transient Blocking
05102GOF	200	300
05104GOF	400	500
05106GOF	600	700
05108GOF	800	900
05110GOF	1000	1100
05112GOF	1200	1300

To specify dv/dt other than 200V/usec., contact factory.

- dv/dt-200 V/usec
- 1200 Amperes surge current
- Hi-Rel Ceramic Header

### Electrical Characteristics

Max. RMS on-state current	$I_{T(RMS)}$ 80 Amps	$T_C = 94^\circ C$
Max. average on-state cur.	$I_{T(AV)}$ 50 Amps	$T_C = 94^\circ C$
Max. peak on-state voltage	$V_{TM}$ 2.5 Volts	$I_{TM} = 500 A(\text{peak})$
Max. holding current	$I_H$ 200 mA	$T_C = 94^\circ C$ 60Hz
Max. peak one cycle surge current	$I_{TSM}$ 1200 Amps	$t = 8.3 \text{ ms}$
Max. $I^2t$ capability for fusing	$I^2t$ 6000A <sup>2</sup> S	

### Thermal and Mechanical Characteristics

Operating junction temp range	$T_J$	-65°C to 150°C
Storage temperature range	$T_{STG}$	-65°C to 150°C
Maximum thermal resistance	$R_{\theta JC}$	0.35°C/W Junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.20°C/W Case to sink
Mounting torque		25-30 inch pounds
Weight		0.63 ounces (18 grams) typical

**LAWRENCE**  
**Microsemi** 6 Lake Street  
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04-24-07 Rev. 2

# 051

$T_J = 25^\circ\text{C}$  unless otherwise indicated

Switching			
Critical rate of rise of on-state current (note 1)	$di/dt$	200A/usec.	$T_J = 125^\circ\text{C}$
Typical delay time (note 1)	$t_d$	3.0 usec.	
Typical circuit commuted turn-off time (note 2)	$t_q$	100 usec.	$T_J = 125^\circ\text{C}$
Note 1: $I_{TM} = 50\text{A}$ , $V_D = V_{DRM}$ . $V_{GT} = 12\text{V}$ open circuit, 20 ohm-0.1 usec. rise time Note 2: $I_{TM} = 50\text{A}$ , $di/dt = 5\text{A/usec.}$ , $V_R$ during turn-off interval = 50V min., reapplied $dv/dt = 20\text{V/usec.}$ , linear to rated $V_{DRM}$ , $V_{GT} = 0\text{V}$			

Triggering			
Max. gate voltage to trigger	$V_{GT}$	3.0V	$T_J = 125^\circ\text{C}$
Max. nontriggering gate voltage	$V_{GD}$	0.25V	
Max. gate current to trigger	$I_{GT}$	100mA	$t_p = 10\text{ usec.}$
Max. peak gate power	$P_{GM}$	10W	
Average gate power	$P_G(\text{AV})$	1.0W	
Max. peak gate current	$I_{GM}$	3.0A	
Max. peak gate voltage (forward)	$V_{GM}$	20V	
Max. peak gate voltage (reverse)	$V_{GM}$	10V	

Blocking			
Max. leakage current	$I_{DRM}$	6mA	$T_J = 125^\circ\text{C}$ & $V_{DRM}$
Max. reverse leakage	$I_{RRM}$	6mA	$T_J = 125^\circ\text{C}$ & $V_{RRM}$
Critical rate of rise of off-state voltage	$dv/dt$	200V/usec.	$T_J = 125^\circ\text{C}$

Figure 1  
Typical Forward On-State Characteristics

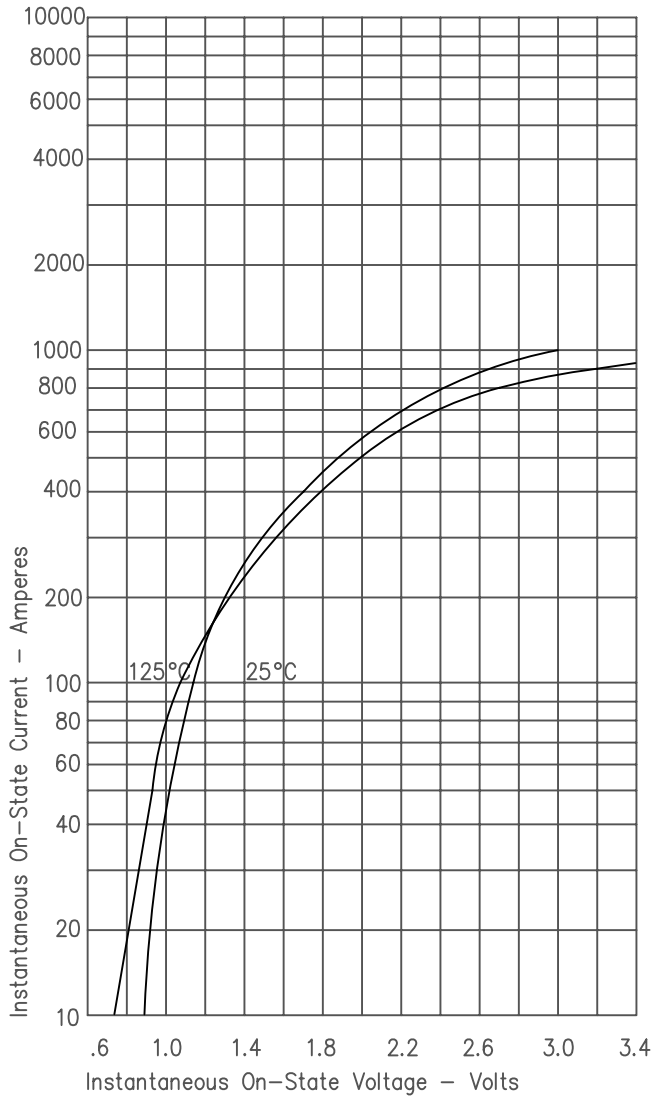


Figure 3  
Maximum Power Dissipation

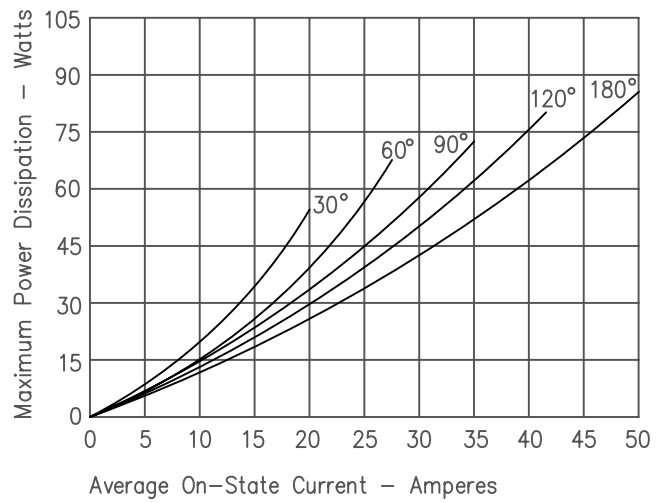


Figure 4  
Transient Thermal Impedance

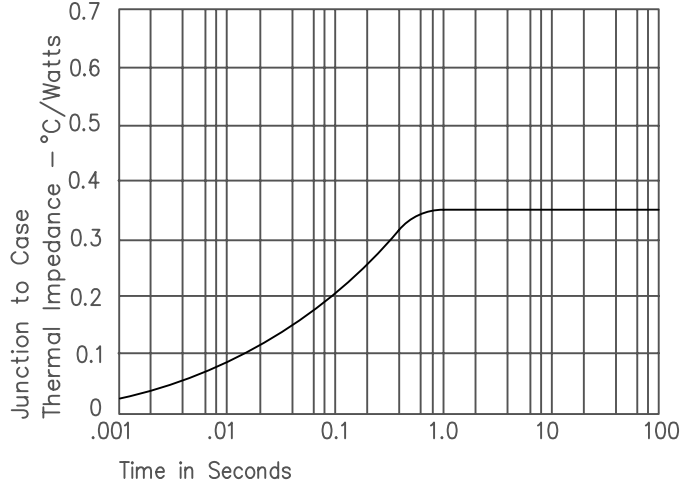


Figure 2  
Forward Current Derating

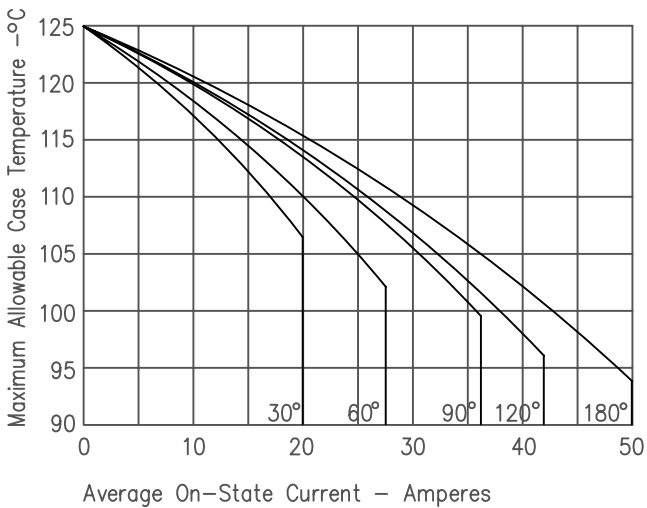


Figure 5  
Maximum Nonrepetitive Surge Current

